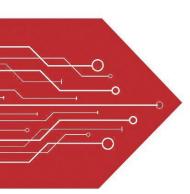
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Broduct data speet

1.1 Technology Data	Symbol		Value	Unit
Maximum allowable continuous AC voltage at 50-60Hz	V _{RMS}		18	V
Maximum allowable continuous DC voltage	V_{DC}		12	V
Varistor voltage measured *1	Vv		100~150	V
Typical capacitance value measured at 1MHz	С		1	pF
Typical capacitance value tolerance			+80-20	%
Maximum ESD allowable clamping Voltage*2	V_{CLAMP}	<	200	V
Leakage current at V _{DC*3} (At initial state)	I _{LDC}	<	0.1	uA
Leakage current at V _{DC*3} (After ESD Test)	I _{LDCA}	<	2	uA
1.2 Reference Data				
Response time	T _{rise}	<	0.5	ns
Operation ambient temperature			-50∼ + 85	$^{\circ}\! C$
Storage temperature			-50~+125	$^{\circ}\! C$
ESD testing	IEC61000-4-2		level 4	
1.3 Other Data				
Body			ZnO	
End termination			Ag/Ni/Sn	
Packaging			Reel	
Complies with Standard			IEC61000-4-2	
Complies with RoHs Standard			Yes	
Lead Content		<	1000	ppm
Marking			None	

Notes:

- $\,st\,$ 1 The varistor voltage was measured at 1 mA current
- * 2 The Clamping voltage was measured at 8*20 us standard current.
- * 3 The Leakage current was measured at working voltage.
- * 4 The Energy only for customer reference.
 * 5 The components shall be employed within 1 year, in the nitrogen condition.

PACKAGE MECHANICAL DATA

Dimension	(Unit:mm)			
	Min.	Max.		
А	0.4	0.6		
В	1.4	1.8		
С	0.5	0.6		
D	0.6	1.2		

0402

The IR reflow and temperature of Soldering for Pb Free

☆ IR reflow Pb Free Process suggestion profile

- (1) The solder recommend is Sn96.5/Ag 3.5 of 120 to 150 μ m
- (2) Ramp-up rate (217°C to Peak) + 3°C/second max
- (4) Temp. maintain above 217 °C 60-150 seconds

REEL SPECIFICATION

P/N	PKG	QTY
SURGE04B03-MS	0402	10000





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